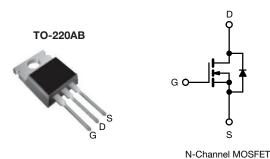
Vishay Siliconix

E Series Power MOSFET



PRODUCT SUMMARY				
V_{DS} (V) at T_J max.	650			
R _{DS(on)} max. at 25 °C (Ω)	V _{GS} = 10 V	0.6		
Q _g max. (nC)	40			
Q _{gs} (nC)	5			
Q _{gd} (nC)	9			
Configuration	Single			

FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (C_{iss})
- Reduced switching and conduction losses
- Ultra low gate charge (Q_a)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION				
Package	TO-220AB			
Lead (Pb)-free	SiHP7N60E-E3			
Lead (Pb)-free and halogen-free	SiHP7N60E-BE3 ^a			
	SiHP7N60E-GE3			

Note

a. "-BE3" denotes alternate manufacturing location

ABSOLUTE MAXIMUM RATINGS (T_C	= 25 °C, unless otherw	ise notea)			
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V	600		
Drain-source voltage	$T_C = -25 ^{\circ}C, I_D = 250 \mu A$	V _{DS}	575	V	
Gate-source voltage		V_{GS}	± 30	1	
Continuous drain current (T _J = 150 °C)	V_{GS} at 10 V $T_{C} = 25 ^{\circ}C$ $T_{C} = 100 ^{\circ}C$		7		
	$T_C = 100 ^{\circ}$ C	l _D	5	Α	
Pulsed drain current ^a		I _{DM}	18		
Linear derating factor			0.63	W/°C	
Single pulse avalanche energy b		E _{AS}	43	mJ	
Maximum power dissipation		P_{D}	78	W	
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	°C	
Drain-source voltage slope	T _J = 125 °C	dV/dt 70		V/ns	
Reverse diode dV/dt ^d			3	V/IIS	
Soldering recommendations (peak temperature) c	For 10 s		300	°C	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature b. $V_{DD}=50$ V, starting $T_J=25$ °C, L=13.8 mH, $R_g=25$ Ω , $I_{AS}=2.5$ A
- 1.6 mm from case
- d. $I_{SD} \le I_D$, dI/dt = 100 A/µs, starting $T_J = 25$ °C



Vishay Siliconix

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R _{thJA}	-	62	°C/W
Maximum junction-to-case (drain)	R _{thJC}	-	1.6	C/VV

PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static				l	ı	•	
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		609	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	Reference to 25 °C, I _D = 1 mA		0.68	-	V/°C
Gate-source threshold Voltage (N)	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$		2	-	4	V
Cata aguras laglaga	1	V _{GS} = ± 20 V		-	=.	± 100	nA
Gate-source leakage	I_{GSS}	$V_{GS} = \pm 30 \text{ V}$		-	-	± 1	μΑ
Zero gate voltage drain current		V _{DS} =	600 V, V _{GS} = 0 V	-	-	1	
Zero gate voltage drain current	I _{DSS}	$V_{DS} = 480 \text{ V}$	V _{DS} = 480 V, V _{GS} = 0 V, T _J = 125 °C		-	10	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	$I_D = 3.5 A$	-	0.5	0.6	Ω
Forward transconductance	9 _{fs}	V _{DS} =	= 50 V, I _D = 3.5 A	-	1.9	-	S
Dynamic							
Input capacitance	C _{iss}	$V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ V},$ f = 1 MHz		-	680	-	
Output capacitance	C _{oss}			-	39	-	
Reverse transfer capacitance	C_{rss}			-	5	-	
Effective output capacitance, energy related ^a	C _{o(er)}	V _{DS} = 0 V to 480 V, V _{GS} = 0 V		-	34	-	pF
Effective output capacitance, time related ^b	$C_{o(tr)}$			-	100	-	
Total gate charge	Qg			-	20	40	
Gate-source charge	Q _{gs}	V _{GS} = 10 V	$V_{GS} = 10 \text{ V}$ $I_D = 3.5 \text{ A}, V_{DS} = 480 \text{ V}$	-	5	-	nC
Gate-drain charge	Q _{gd}				9	-	
Turn-on delay time	t _{d(on)}	$V_{DD} = 480 \text{ V}, I_{D} = 3.5 \text{ A}, V_{GS} = 10 \text{ V}, R_{g} = 9.1 \Omega$		-	13	26	
Rise time	t _r			-	13	26	200
Turn-off delay time	t _{d(off)}			-	24	48	ns
Fall time	t _f		1		14	28	
Gate input resistance	R _g	f = 1 MHz, open drain		-	1.1	-	Ω
Drain-Source Body Diode Characteristic	s						
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	7	_
Pulsed diode forward current	I _{SM}			-	-	18	A
Diode forward voltage	V _{SD}	T _J = 25 °C, I _S = 3.5 A, V _{GS} = 0 V		-	-	1.2	V
Reverse recovery time	t _{rr}	$T_J = 25 ^{\circ}\text{C}, I_F = I_S = 3.5 \text{A},$ $dI/dt = 100 \text{A/}\mu\text{s}, \text{V}_R = 20 \text{V}$		-	230	-	ns
Reverse recovery charge	Q _{rr}			-	1.9	-	μC
Reverse recovery current	I _{RRM}			-	14	-	A

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

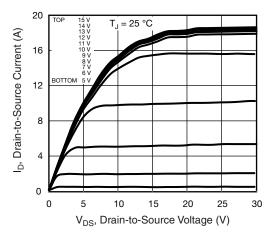


Fig. 1 - Typical Output Characteristics

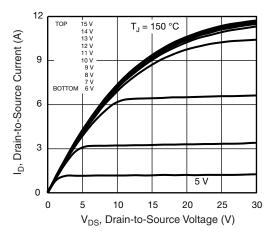


Fig. 2 - Typical Output Characteristics

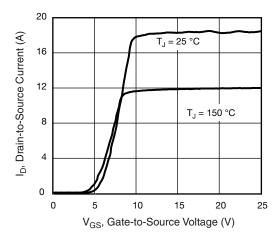


Fig. 3 - Typical Transfer Characteristics

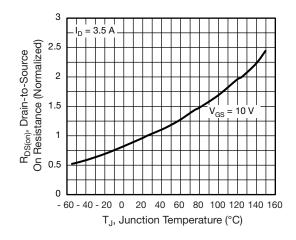


Fig. 4 - Normalized On-Resistance vs. Temperature

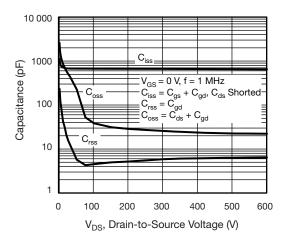


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

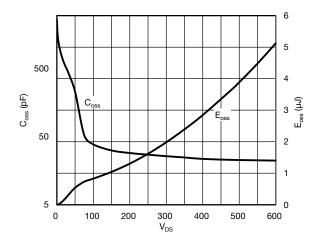


Fig. 6 - Coss and Eoss vs. VDS



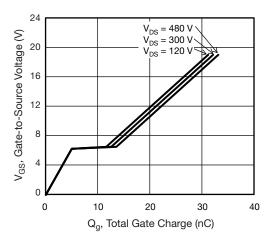


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

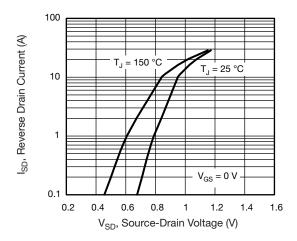


Fig. 8 - Typical Source-Drain Diode Forward Voltage

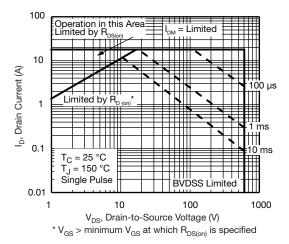


Fig. 9 - Maximum Safe Operating Area

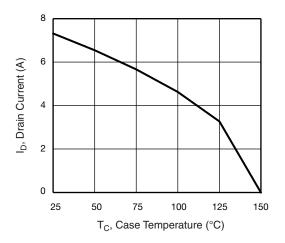


Fig. 10 - Maximum Drain Current vs. Case Temperature

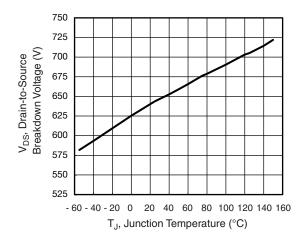


Fig. 11 - Temperature vs. Drain-to-Source Voltage



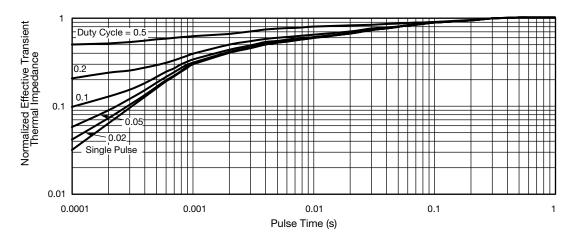


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

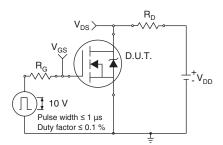


Fig. 13 - Switching Time Test Circuit

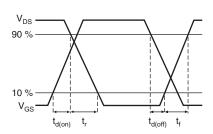


Fig. 14 - Switching Time Waveforms

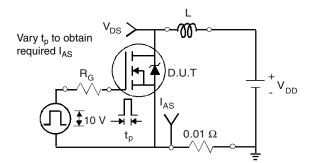


Fig. 15 - Unclamped Inductive Test Circuit

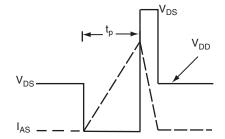


Fig. 16 - Unclamped Inductive Waveforms

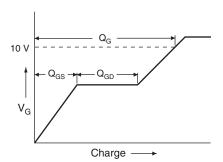


Fig. 17 - Basic Gate Charge Waveform

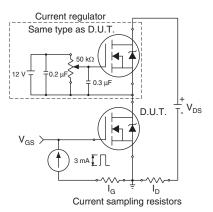
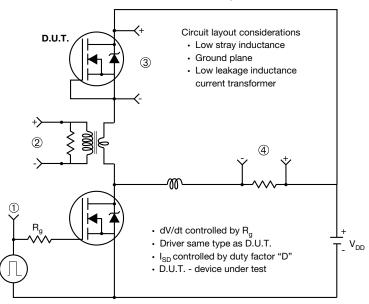


Fig. 18 - Gate Charge Test Circuit

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Peak Diode Recovery dV/dt Test Circuit



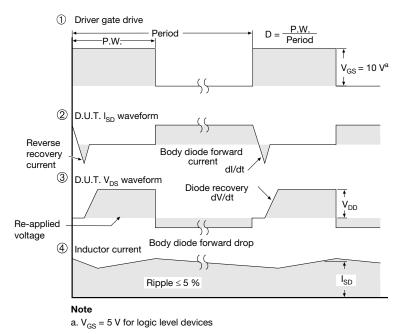


Fig. 19 - For N-Channel

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